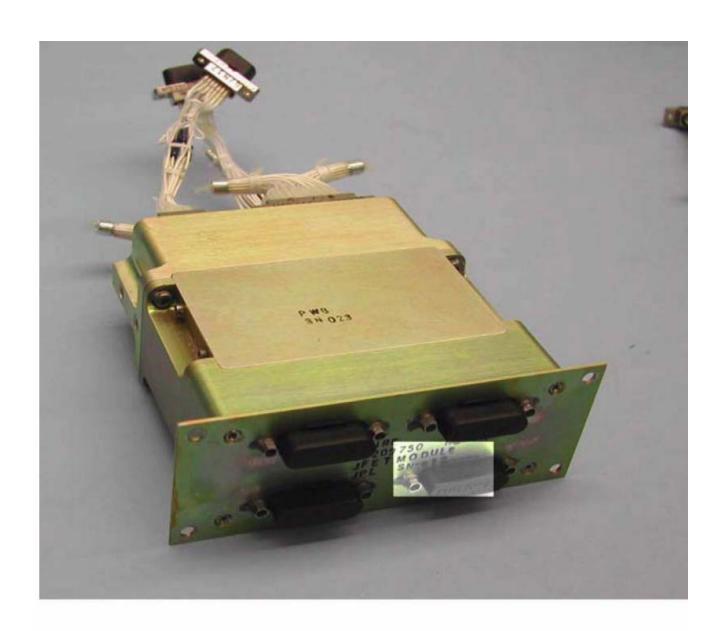
JPL Hardware Requirements Certification Review – SPIRE Element No. D-30473

Assembly / Subsystem		PE	M			Phone		Section		Date
SPIRE		Ma	rtin	Herr	nan	(818) 354-8	541	386		3 February, 2005
Drawing/ Part No.	Dwg. Rev.	No	men	clati	ure	Serial No.	Model	Туре	Final IR No.	Mass (Meas. / Req.)
10209750-1	В	JF	ET N	lodu	le	012	FLIGHT	N/A	923845	275.8 gm / 305 gm
Check applicable answer a explanation in remarks col		Y E S	N O	N A	Re	marks		Data	Attachments	Signature & Date
1. Are all drawings and spec complete, approved, released		Х						14. Latest Top ⊠ Attached	Assembly drawings None	Cognizant Engineer
2. Do the released drawings specifications reflect all appro		Х					2.	15. List of open Attached	ECRs None	PEMartin for 2/19/0
3. Is hardware identical to ot delivered? If no, provide difference of the control of the contro		Х						16. Waivers (RI	FW request for waiver) None	Of Engineer Also
4. Does the hardware meet it requirements, specifications,		Х			EIDP attached. Also see item # 8	3 attachments		17. Open MRB Attached	None Non	Environments/Reliability
5. Are all IR and MRB disposed concurred by QA?	sitioned and	X		,				18. Open PFR o	on this H/W None	Mission Assurance Mgr.
6. Is complete as-built list infincluded in the build book?	formation	X						19. Open PFR o	on similar H/W None	Project Office
7. Have all required environr analyses been completed?	nental tests &	Х			ETAS attached			20. Handling Do	ocument → See Item 11 ☐ None	R1 ems Jule 2/18/05
8. Is all required assembly a subsystem level functional te		Х			Performance Tes Also see EIDP in		ed.	21. Shortage Li Attached	st 🖂 None	
9. Have all piece parts, procematerials been approved by		Х						22. Requireme	nts Verification Matrix ee #4, #7, #8)	
10. Does this hardware mee contamination control require		х			Parts, processes contamination co requirements.			23. Qualificatio	n Status None	
11. Are all shipping containe special handling procedures	ready?	Х		3	See Attached Do	cument D-26	790	24. Mate / Den Attached	nate Record None	
12. Is additional work require hardware to flight readiness?			Х					25. Operating L Attached (S		
13. Is this hardware accepta	ble for flight?	X		7				26. MICD	None	



SPIRE JFET Module S/N 012

RAL EIDP Table of Contents Versus JPL HRCR Check List Item Numbers

RAL EIDP Section	RAL EIDP Title	JPL HRCR Check List Item Number	Notes
Number		Tiem Tumber	
1	Shipping Documents		Shipper and Final IR
2	Transportation, Packing, Handling & Integration Procedures	11	Special Handling Document D-26790
3	Certificate of Conformance / Delivery Review Board MOM		HRCR book is the C of C
4	As Built Configuration Status List	1 & 2	Assembly Drawings
5	List of Waivers	4	RFW (request for waiver) Attached
6	Copies of Waivers	4 & 7	RFW (request for waiver) Attached
7	List of Non-Conformance Reports		See RFW in 4 & 7
8	Copies of Non-Conformance Reports		See RFW in 4 & 7
9	Cleanliness Statement		Final IR QA Inspection
10	Operational Manual		NA
11	Top Level Drawings (inc. Family Tree)	14	Top Assembly Drawing
12	Interface Drawings	26	MICD Drawing
13	Functional, Block & Mechanical Drawings		NA
14	Electrical Circuit Drawings		NA
15	Serialized Components List		In build books – not shipped
16	Mass Properties/ Power Budget	HRCR Check List Page 1	Mass listed in HRCR check list
17	Qualification Status List / Test Matrix	23	Qualification Unit Test Matrix
18	Test Reports	4, 7, 8, 23	
19	Open Work / Deferred Work / Open Tests		NA
20	Calibration Data		NA
21	Historical Record	23	Qualification Unit Test Matrix
22	Manufacturing Logbook(s)		In build books – not shipped
23	Operating Time / Cycle Record	25	
24	Connector Mating Record	24	
25	Age Sensitive Items Record		NA
26	Pressure Vessels – History/Test Record		NA
27	Temporary Installation Record		NA
28	Reference List of EIDPs (Lower level)		NA
29	Other Useful Information	_	NA

JPL Hardware Requirements Certification Review (HRCR)

Junction Field Effect Transistor (JFET) Flight Module

10209750-1 S/N 012

SPIRE Element
Herschel Space Observatory Project

February 3, 2005

Configuration of Module, Boards & Membranes

Module 10209750-1	S/N 12	S/N 12
PWB 10209760-1	S/N 22	S/N 23
Membrane 10209758-1	J5.6.2	J5.6.3

Attachment of HRCR Items #1 Drawing Release Status

ALL ASSEMBLY & PARTS DRAWINGS ARE RELEASED IN PDMS

Released Drawings:

10209719-1	assembly built per released Rev. A drawing (studlock)
10209722-1	assembly built per released Rev. B drawing (interface drawing)
10209750-1	assembly built per released Rev. B drawing (module assy)
10209751-1	assembly built per released Rev. B drawing (chassis 1)
10209752-1	assembly built per released Rev. A drawing (chassis 2)
10209753-1	assembly built per released Rev. A drawing (chassis 3)
10209754-1	assembly built per released Rev. C drawing (mount)
10209756-1	assembly built per released Rev. B drawing (chassis lid)
10209757-1	assembly built per released Rev. A drawing (membrane)
10209758-1	assembly built per released Rev. A drawing (membrane assy)
10209759-1,-2	2,-4 redlined Rev. B drawing (gasket)
10209760-1	assembly built per released Rev. C drawing (board assembly)
10209761-1	assembly built per released Rev. C drawing (solder connector)
10209769-1	assembly built per released Rev. A drawing (stiffener)
10209777-1	assembly built per released Rev. B drawing (board)
10209858-2	assembly built per released Rev. A drawing (special fastener)
10217636-1	assembly built per released Rev. A drawing (clip)

Attachment of HRCR Item #4: EIDP

		EIDP	Coverpage	For JFET	Testing	I	
Unit Identfication							
Name	:	JFET PF	M Module				
Part #	:		9750-1				
S/N	:_	#0)12				
Fi	=						
Environmemtal Testing							
		Axes Tested	Temp	Duration/# of Cycle	Requirement	Source	Waiver
		resteu	remp	or oyor.	requirement	SSSD.	Truite.
Random Vibration Test		X, Y, Z	Rm T	1 min/axis	X, Y, Z	JFET-DES-07	
						SSSD,	HR-SP-JPL-
High Level Sine Vibe Test		None	NA	NA	X, Y, Z	JFET-DES-07	RFW-005
Bakeout		NA	80 C	25 hrs	> 24 HRS		
Thermal Cycles		NA	RmT to 80 K	2	Minimum 1	D-20549	
Performance Characteristics							
T Griorinano Grianacione			Specific	cation		Source	Waiver
Power needed for <11 bad channels			11 mW fo			SSSD,	HR-SP-JPL-
(Min Perf.)		8.00 mW	7 mW for f	PFM/FS	JFET-TEC	-05, JFET-PER-02	RFW-004
Power needed for <4 bad channels			11 mW fo			SSSD,	
(Design Value) Power needed for 100 %		8.29 mW	7 mW for f	PFM/FS	JFET-TEG	-05, JFET-PER-02	
Yield per unit		8.98 mW	N.A			NA	
Median Noise at < 11 bad chs.		9.29 nV/rtHz			SSSD.	JFET-PER-01	
Median Noise at < 4 bad chs.		8.19 nV/rtHz	<15 nV/rtHz Min	<7 nV/rtHz Design		JFET-PER-01	
Median Noise at 100 % Yield.		7.87 nV/rtHz	Performance	Value		, JFET-PER-01	
# of Channels over the						SSSD,	
max. offset voltage		0	< 15 mV			BDA-DRCU-27	
Common Mode Rejection Ratio Board Level Details		< -60 dB by de	sign, as measu	red in EM4 ur	nit	SSSD, BDA-DRCU-11	
Board Level Details		Based	231.000	Des	1.011.000		
			SN 022 '-JDD')		ard SN 023 IAA-JDD)	Source	
# Channels Tested		24	500)	24	1000	300100	
# Originiels Tested						SSSD,	
Median Noise at 3.5 mW	:	12.48	nV/rtHz	19.	87 nV/rtHz	JFET-PER-01	
# of good channels			58.3%		29.2%	SSSD,	
at 3.5 mW Power Needed for	:	14	Yield	7	Yield	JFET-PER-02	
100 % Yield		4.57 mW		4.41 mW		SSSD, JFET-PER-02	
Median Noise at High Power (w/ 100		4.07 1111		4.41		SSSD,	
% Yield)		8.28 r	nV/rtHz	7.4	11 nV/rtHz	JFET-PER-01	
Median Gain at High Power		0.	.98		0.98	NA	
Heater Resistance, 4K Reference value		3.23	3 kΩ		3.5 kΩ	NA	
Definitions							
Good Channels	:		n a min. perform	ance value o	f 15 nV/rtHz		
Yield	:	# of Good Cha	nnels / 24				
Filenames	H	IEEE Madda	1 400 00 Nais				
Noise Measurements Source Voltages (RmT, 4K)	<u>:</u>		_brd22, 23_Nois 12 15 voltage da				
Notes	·	JET Module	12,15 voltage da	ita.pur			
The Base temperature for all performance		characterizatio	o was dk				
All Noise Measurements were made with	th t	ne inputs shorte	ed to ground				

SN022: 31% Overetched

Type of membranes:

SN023: 33% Overetched

Attachment of HRCR Item #4: RFW (request for waiver)

		RFW/RFD Number:	HR-SP-JPL	RFW-013
Spacecraft / Project	Herschel	Originator's Name	Steve Tseng	
System / Experiment / Model	1.1 SPIRE	Signature / Date		
Sub-System	detectors	Request Type (Highlight applicable request)	Waiver (RFW)	Deviation (RFD)
Assembly	JFET modules	1.1.1.1 Organisation	Jet Propulsion	Laboratory
Sub-Assembly		Ref. Doc. / Drwg No.	SPIRE-JPL-P	RJ-000456
Item		References		
Serial No.		I/CICICIICC3		
RFW/RFD Title	JFET Power Dissipation s/n 01	2		

	End Items	s(s) Affected (Hardw	are, Software)	
Name		CI-Nu	mber		Model(s)
JFET Module p/n 10209750 s/n 012				PF	M
F	Requirem	ent / Interface Docu	ments Affecte	ed	
Specification/Drawing Title		Number	Issue	Date	App. Paragraph
BDA-SSSD	SPIRE-	JPL-PRJ-0004456	3.2	7/1/03	JFET-PER-01 JFET-PER-02 JFET-TEC-05
Descript	tion of De	eviation / Discrepand	cy / Non-Conf	ormance	

Requirement states that dissipation of photometer JFETs is to be less than 7 mW average, while supplying 90% of channels with voltage noise < 15 nV/rtHz according to BDA-SSSD JFET-PER-01, JFET-PER-02, JFET-TEC-05. Measured JFET performance of the JFETs indicates that 8 mW of power dissipation will be required to meet the specified yield and noise performance specifications.

Other Items or Requirements (Potentially) Affected

Overall sensitivity of the bolometer sub-system is affected by JFET noise performance. JFET power dissipation impacts the heat sink temperature of the 3He refrigerator and may in turn increase the base detector temperature. Dissipation of JFETs affects power dissipation on cryostat.

Need for RFW/RFD and Rationale for Acceptance

Measured JFET performance of JFETs indicates that 8 mW of power dissipation will be required to meet the specified yield and noise performance specifications. JPL is unable to significantly alter the JFET fabrication process in order to meet the power specification without undue risk to the stated PFM/FS delivery dates. Furthermore, JPL requests a full system optimisation to revisit the noise and power requirements on the JFETs. The JFET modules can meet the noise design value with 100 % yield at 8.98.

	Approved	Rejected	Name	Date
Engineering:				
Product Assurance:				
CCB-Chairman:				
Principal Investigator				
Product Assurance:				
Co-Investigator				
Prime Contractor				
ESA Project Office				

Attachment of HRCR Item #7: RFW (request for waiver)

		RFV	V/RFD Number:	Н	R-SP-JPL-F	RFW-005
Spacecraft / Project	Herschel		Originator's Name		Kalyani Sukhatme	9
System / Experiment / Model	SPIRE		Signature / Date			
Sub-System	detectors		Request Type (Highlight applicable reque	est)	Waiver (RFW)	Deviation (RFD)
Assembly			Organisation		Jet Propulsion	1 Laboratory
Sub-Assembly			Ref. Doc. / Drwg No.		SPIRE-JPL-PF	RJ-000456
Item			References			
Serial No.			References			
RFW/RFD Title	BDA and JFET module s	sine te	st deletion			_

l l	End Items(s) Affected (Ha	rdware, Softwar	e)	
Name	CI-	Number		Model(s)
Bolometric Detector Assemblies JFET Modules			CC	QM, PFM, FS QM, PFM, FS
	equirement / Interface Do	ocuments Affect	1	
Specification/Drawing Title	Number	Issue	Date	App. Paragraph
BDA-SSSD (SPIRE-JPL-PRJ- 000456)		3.2	Jan 7, 2003	BDA-DES-10, JFET-DES- 07
Descript	ion of Deviation / Discrep	ancy / Non-Con	formance	•
Othe	er Items or Requirements	(Potentially) Aff	ected	

The hardware has to be qualified under a cold vibration test and is installed in the cold vibration facility for the purpose of the test. The high level sine vibration test configuration will put the hardware and the personnel at risk since the cold vibration facility is not structurally capable of withstanding the high levels. Obtaining additional resources (cost and schedule) for developing a new set-up is not feasible at this time.

	Approved	Rejected	Name	Date
JPL Engineering:				
JPL Product Assurance:				
CCB-Chairman:				
Principal Investigator				
Product Assurance:				
Co-Investigator				
Prime Contractor				
ESA Project Office				

Attachment of HRCR Item #7: ETAS (environmental test summary) ETAS No. HS 037

MADOWARE TYPE		AUTHOR	IZATION SECTIO)N	
STEMASSEABLY TITLE					
PART NO, FAULTPLE, ATTACH LIST) REV. SERIAL NO. O12, 015				Hado	
MADOWARE TYPE		DADT NO (IEASII TIDLE AT	TTACHLIST)	DEV	
PHI OUAL PLIGHT PLIGHT SPARE OTHER OTHER PART NO. REV. SERIAL NO.	S ENERGE DESIGNATION NOMBER		· · · · · · · · · · · · · · · · · · ·		
MENING MARNESS EM QUAL PLIGHT EM SE MARY SERVAL NO. REV. SERVAL NO. REV. SERVAL NO. REV. SERVAL NO. REV. SERVAL NO. PYROSHOOK ACQUISTIC EMC OTHER TYPE OF TEST		T FLIGHT SPARE	□ OTHER	PRE-ENVIRONMENTAL INS	PECTION REPORT NUMBER (ATTACH IR)
EST DESCRIPTION (CHECK ALL APPLICABLE) SAVE WISHARTHON PYROSHOCK ACQUISTIC EMC OTHER QUALIFICATION FLIGHT ACCEP RANDOM VIBRATION MERTING PYROSHOCK ACQUISTIC EMC OTHER QUALIFICATION FLIGHT ACCEP RANDOM VIBRATION MERTING PYROSHOCK ACQUISTIC EMC OTHER QUALIFICATION FLIGHT ACCEP RANDOM VIBRATION MERTING PYROSHOCK SLOT PRETIST RETEST QUALIFICATION FLIGHT LINES YES	IRING HARNESS			REV.	SERIAL NO.
SINE VIBRATION PYROSHOCK ACOUSTIC CM OTHER QUALIFICATION FLIGHT ACCEP RANDOM VIBRATION THERMAL AVA. THERMAL		EMSE	L	TYPE OF TEST	
NILL ALL TESTSLEVES DURATIONS REQUIRED BY THE PROJECT DOCUMENTS BE PERFORMED ON THIS UNIT? YES	SINE VIBRATION PYROSHOCK		OTHER	QUALIFICATION	FLIGHT ACCEPTANCE
YES		The second secon	PERFORMED ON THIS	Name and the second	RETEST
NO (IF NO, ATTACH EXCEPTIONS LIST)					
AVE ALL DESIGN ANALYSES BEEN COMPLETED AND REQUIRED CHANGES BEEN IMPLEMENTED? YES					
YES			41.00		
THE TEST ARTICLE IDENTICAL TO OTHER FLIGHT UNITS? YES					
BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been addressed and See PFR # 284742 and 284924 BRIEF EXPLANATION PFR's in process of dosure. All issues have been	THE TEST ARTICLE IDENTICAL TO OTHER FLIGHT U	JNITS?			
See PER 284742 and 284924 BRIEF EXPLANATION PFR's in process of closure. All issues have been addressed and see PER 284742 and 284924 BRIEF EXPLANATION TEST AUTHORIZED BY DATE DATE TECHNICAL MIGRAINSTR MRG,PI PREP DATE BRIEF EXPLANATION TEST AUTHORIZED BY DATE DATE TECHNICAL MIGRAINSTR MRG,PI PREP DATE BRIEF EXPLANATION TEST AUTHORIZED BY DATE DATE TEST INITIATION DATE ACCUMULATED OPERATING HOURS PRIOR TO FIRST ENVIRONMENTAL EXPOSURE TEST TERMINATION DATE OPERATING HOURS DURING ENVIRONMENTAL EXPOSURE TEST DESCRIPTION TEST DESCRIPTION TEST DESCRIPTION TEMPLEVEL ("G) AND ACCUMULATED DURING HOURS DURING HER HOURS DURING HOURS		XCEPTIONS LIST)	BRIEF EXPLANATION	<u> </u>	
SPECIAL WAIVERS AND ECRS BEEN APPROVED AND ARE THEY INCORPORATED?		XCEPTIONS LIST)			sues have been addressed and qualified.
TEST AUTHORIZED BY COGNIZANT ENGINEER DATE TECHNICAL MIGRAINSTR MIRG./P) PREP REP DATE SUMMARY SECTION EST AGENCY (IF MULTIPLE, ATTACH SUMMARY AND TEST DATES) PL Building 144 ERIAL NUMBERS ACTUALLY TESTED TEST TEST DESCRIPTION VIBRATION ACCUMULATED OPERATING HOURS PRIOR TO FIRST ENVIRONMENTAL EXPOSURE TEST DESCRIPTION VIBRATION AXES: X Y Z AXES: X Y Z AXES: X Y Z AXES: X Y Z AND OF CYCLES: NO OF CYCLES:			7	LUTTUET	
TEST DESCRIPTION VIBRATION VIBRATION ACOUSTIC PYROSHOCK SHOCK AXES: X Y Z BINCOMD SUSC. COND. BMIS. SHOCKS/AXIS: COND. SUSC. COND. BMIS. SHOCKS/AXIS: MAGNETICS MAG	YES NO (IF NO, ATTACH E				<u> </u>
SUMMARY SECTION TEST AGENCY (IF MULTIPLE, ATTACH SUMMARY AND TEST DATES) PL Building 144 11/11/04 SERIAL NUMBERS ACTUALLY TESTED TEST DESCRIPTION VIBRATION AXES: X Y Z SINE VIBRATION AXES: X Y Z SINE VIBRATION S	71.11	ATE TECHNICAL MGR./INST		DATE ENVIRONMENTA	1
TEST INITIATION DATE ACCUMULATED OPERATING HOURS PRIOR TO FIRST ENVIRONMENTAL EXPOSURE	11/11/10	3 Wash	. /		
TEST DESCRIPTION TEMPERATURE ATMOSPHERE OF CALLS, X Y Z ALS; X Y	THE RESIDENCE OF THE PARTY OF T	CHIERRY	LADY CECTION	11/2 1001	lewey 2-7-05
TEST TERMINATION DATE OPERATING HOURS DURING ENVIRONMENTAL EXPOSURE TEST DESCRIPTION VIBRATION VIBRATION ACOUSTIC PYROSHOCK SHOCK AXES: X Y Z AXES: X Y Z RANDOM VIBRATION SHOCKS/AXIS: SHOCKS/AXIS S		PERSONAL MEDICAL MEDICAL PROPERTY OF	CARL CARLO SECURIO SERVICIO	AU ATER ODERATING HOUSE B	
VIBRATION ACOUSTIC PYROSHOCK SHOCK AXES: X Y Z AXES:		TEST DATES) TEST INITIA	CARL CARLO SECURIO SERVICIO	JULATED OPERATING HOURS P	
VIBRATION ACOUSTIC PYROSHOCK SHOCK AXES: X Y Z AXES: X	PL Building 144	TEST DATES) TEST INITIA 11/11/04	ATION DATE ACCUM		RIOR TO FIRST ENVIRONMENTAL TEST
AXES: X Y Z AXES: X Y Z AXES: X Y Z PRESSURE: <10E-5 <77K \R.T. C \K.	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED	TEST DATES) TEST INITIA 11/11/04	ATION DATE ACCUM		RIOR TO FIRST ENVIRONMENTAL TEST
SINE VIBRATION	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED	TEST DATES) TEST INITIA 11/11/04 TEST TERMIN	NATION DATE OPERA	ATING HOURS DURING ENVIRON	RIOR TO FIRST ENVIRONMENTAL TEST
ANDOM VIBRATION SHOCKS/AXIS: NO OF CYCLES: ************************************	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED 5 ハ 1 ス ・1 5 VIBRATION ACOUSTIC	TEST DATES) TEST INITIA 11/11/04 TEST TERMIN TEST PYROSHOCK SHOCK	NATION DATE ACCUMINATION DATE OPERA T DESCRIPTION THERMAL	ATING HOURS DURING ENVIRON	RIOR TO FIRST ENVIRONMENTAL TEST
MC COND. SUSC. COND. EMIS. SOLATION TEMP. LEVEL ("c) AND ACCUMULATED DURATION (HRS BSD RAD. SUSC. RAD. EMIS. MAGNETICS HOT: "c, h COLD: "c HOT: "c, h COLD: "c, h	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED 5 / 1 / 2 - 1 / 5 VIBRATION ACOUSTIC AXES: X Y Z	TEST DATES) TEST INITIA 11/11/04 TEST TERMIN TEST PYROSHOCK SHOCK AXES: X Y	NATION DATE ACCUM	VACUUM TEMPERATU	RIOR TO FIRST ENVIRONMENTAL TEST
ESD RAD. SUSC. RAD, EMIS. MAGNETICS HOT: °C, h COLD: °C WERE THERE ANY PFRS GENERATED DURING ENVIRONMENTAL TESTS? LIST PFR NOS. / BRIEF IEXPLANATION LIST PFR NOS. / BRIEF IEXPLANATION WERE THE POST ENVIRONMENTAL DAMAGE INSPECTIONS COMPLETE? NO (IF YES, ATTACH A COPY OF THE INSPECTION REPORTS. IF NO, ATTACH EXPLANATION)	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED 5 / 1 / 2 - 4 - 1 - 5 VIBRATION ACOUSTIC AXES: X Y Z NE VIBRATION	TEST DATES) TEST INITIA 11/11/04 TEST TERMIN TEST PYROSHOCK SHOCK AXES: X Y	ACCUMINATION DATE OPERA T DESCRIPTION Z PRESSURE: <10 <p>THERMAL. Z PRESSURE: <10</p>	VACUUM TEMPERATU	RIOR TO FIRST ENVIRONMENTAL TEST
WERE THERE ANY PFRs GENERATED DURING ENVIRONMENTAL TESTS? JYES NO (IF NO, ATTACH EXCEPTIONS LIST) WERE THE POST ENVIRONMENTAL DAMAGE INSPECTIONS COMPLETE? NO (IF YES, ATTACH A COPY OF THE INSPECTION REPORTS. IF NO, ATTACH EXPLANATION)	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SIGN 12 4-15 VIBRATION ACOUSTIC AXES: X Y Z INE VIBRATION ACOUSTIC ANDOM VIBRATION	TEST DATES) TEST INITIA 11/11/04 TESTTERMIN TEST PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS:	T DESCRIPTION Z PRESSURE: <10 <p>< 77K \(\) R.T.</p> NO OF CYCLES	VACUUM TEMPERATU DE-6 1 C VIC IE	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER
YES NO (IF NO, ATTACH EXCEPTIONS LIST) IRE THE POST ENVIRONMENTAL DAMAGE INSPECTIONS COMPLETE? YES NO (IF YES, ATTACH A COPY OF THE INSPECTION REPORTS. IF NO, ATTACH EXPLANATION)	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SIGN 12 4-15 VIBRATION ACOUSTIC AXES: X Y Z INE VIBRATION ANDOM VIBRATION COND. SUSC.	TEST DATES) TEST INITIA 11/11/04 TESTTERMIN TEST PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COND. EMIS.	ACCUMINATION DATE OPERA T DESCRIPTION Z HERMAL PRESSURE: <10	VACUUM TEMPERATU DE-5 1 C V/C e 1 C V/C e 1 TEMP. LEVEL (*c) AND ACC	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER SUMULATED DURATION (HRS.)
ARE THE POST ENVIRONMENTAL DAMAGE INSPECTIONS COMPLETE? JYES NO (IF YES, ATTACH A COPY OF THE INSPECTION REPORTS. IF NO, ATTACH EXPLANATION)	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SAL 12 415 VIBRATION ACOUSTIC AXES: X Y Z NE VIBRATION COND. SUSC. ESD RAD. SUSC.	TEST DATES) TEST INITIA 11/11/04 TEST TERMIN PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COND. EMIS.	ACCUMINATION DATE OPERA T DESCRIPTION Z HERMAL PRESSURE: <10	VACUUM TEMPERATU DE-5 L < \ \cdot c \ TEMP. LEVEL ("c) AND ACC HOT: "C, "C, "C, "C,	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER JUMULATED DURATION (HRS.) h COLD:°C,h
YES NO (IF YES, ATTACH A COPY OF THE INSPECTION REPORTS. IF NO, ATTACH EXPLANATION)	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SAL 12 415 VIBRATION ACOUSTIC AXES: X Y Z ANDOM VIBRATION COND. SUSC. ESD RAD. SUSC. ERE THERE ANY PFRS GENERATED DURING ENVIR	TEST DATES) TEST INITIA 11/11/04 TEST TERMIN PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COND. EMIS. RAD. EMIS. ONMENTAL TESTS?	ACCUM NATION DATE OPERA T DESCRIPTION Z THERMAL Z PRESSURE: <10	VACUUM TEMPERATU DE-5 C V/C e PEMP. LEVEL (°c) AND ACC HOT: °c, HOT: °c,	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER JUMULATED DURATION (HRS.) h COLD:°C,h
REPORTS. IF NO, ATTACH EXPLANATION)	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SAL 12 4-15 VIBRATION ACOUSTIC AXES: X Y Z ANDOM VIBRATION COND. SUSC. ESD RAD. SUSC. ERE THERE ANY PFRS GENERATED DURING ENVIR	TEST DATES) TEST INITIA 11/11/04 TESTTERMIN PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COND. EMIS. RAD. EMIS. ONMENTAL TESTS? XCEPTIONS LIST)	ACCUMINATION DATE ACCUMINATION DATE OPERA T DESCRIPTION Z THERMAL PRESSURE: <10	VACUUM TEMPERATU DE-5 1 C \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER JUMULATED DURATION (HRS.) h COLD:°C,h
	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED S / 1 / 2	TEST DATES) TEST INITIA 11/11/04 TESTTERMIN TEST PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COND. EMIS. RAD. EMIS. ONMENTAL TESTS? CXCEPTIONS LIST) DOS COMPLETE?	ACCUMINATION DATE ACCUMINATION DATE OPERA T DESCRIPTION T HERMAL PRESSURE: <10 <p><77K \ R.T. NO OF CYCLES</p> UIST PFR NOS. LIST PFR NOS.	VACUUM TEMPERATU DE-5 1 C \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER JUMULATED DURATION (HRS.) h COLD:°C,h
	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SOL 12 4-15 VIBRATION ACOUSTIC AXES: X Y Z INE VIBRATION COND. SUSC. ESD RAD. SUSC. ERE THERE ANY PFRS GENERATED DURING ENVIR YES NO (IF NO, ATTACHE RE THE POST ENVIRONMENTAL DAMAGE INSPECTIC YES NO (IF YES, ATTACHE NO (IF YES, ATTACH)	TEST DATES) TEST INITIA 11/11/04 TESTTERMIN TEST PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COND. EMIS. RAD. EMIS. ONMENTAL TESTS? EXCEPTIONS LIST) ONS COMPLETE? A COPY OF THE INSPECTION	ACCUMINATION DATE ACCUMINATION DATE OPERA T DESCRIPTION T HERMAL PRESSURE: <10 <p><77K \ R.T. NO OF CYCLES</p> UIST PFR NOS. LIST PFR NOS.	VACUUM TEMPERATU DE-5 1 C \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER JUMULATED DURATION (HRS.) h COLD:°C,h
YES NO (IF NO, ATTACH EXCEPTIONS LIST)	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SAL 12 - 15 VIBRATION ACOUSTIC AXES: X Y Z NE VIBRATION COND. SUSC. ESD RAD. SUSC. ERE THERE ANY PFRS GENERATO DURING ENVIRONMENTAL DAMAGE INSPECTING YES NO (IF NO, ATTACH E RE THE POST ENVIRONMENTAL DAMAGE INSPECTING YES NO (IF YES, ATTACH E REPORTS. IF NO	TEST INITIA 11/11/04 TEST TERMIN PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COND. EMIS. RAD. EMIS. RAD. EMIS. ONDERTAL TESTS? EXCEPTIONS LIST) DINS COMPLETE? A COPY OF THE INSPECTION O, ATTACH EXPLANATION)	ACCUMINATION DATE ACCUMINATION DATE OPERA T DESCRIPTION Z PRESSURE: <10	VACUUM VACUUM DE-5 C C V C C TEMP. LEVEL ("C) AND ACC HOT: "C, HOT: "C, BRIEF EXPLANATION	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER JUMULATED DURATION (HRS.) h COLD:°C,h
TESTS HAVE NOT BEEN SUCCESSFULLY COMPLETED. SEE THE ATTACHED SUMMARY FOR ACTIONS THAT NEED TO BE TAKEN. DATE TECHNICAL MGRJINSTR MRGJPI PREP REP DATE ENVIRONMENTAL REQUIREMENTS ENG.	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SAL 12 415 VIBRATION ACOUSTIC AXES: X Y Z NE VIBRATION COND. SUSC. ESD RAD. SUSC. ERE THERE ANY PFRS GENERATED DURING ENVIRONMENTAL DAMAGE INSPECTIVE YES NO (IF YES, ATTACH E RE THE POST ENVIRONMENTAL DAMAGE INSPECTIVE YES NO (IF YES, ATTACH E REPORTS. IF NO ERE ALL PLANNED TESTS/LEVELS/DURATIONS ACH YES NO (IF NO, ATTACH E	TEST DATES) TEST INITIA 11/11/04 TEST TERMIN PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COMPLETE: CO	ACCUM NATION DATE ACCUM NATION DATE OPERA T DESCRIPTION Z THERMAL PRESSURE: <10	VACUUM TEMPERATU DE-6 1 C VIC IN TEMP. LEVEL ("C) AND ACC HOT: "C, HOT:	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER JUMULATED DURATION (HRS.) h COLD:°C,h
	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SAL 12 415 VIBRATION ACOUSTIC AXES: X Y Z NE VIBRATION COND. SUSC. ERE THERE ANY PFRS GENERATED DURING ENVIR YES NO (IF NO, ATTACH E RE THE POST ENVIRONMENTAL DAMAGE INSPECTIVE YES NO (IF NO, ATTACH E PER ALL PLANNED TESTS/LEVELS/DURATIONS ACH YES NO (IF NO, ATTACH E TESTS HAVE NOT BEEN SUCCESSFULLY COMPLI	TEST DATES) TEST INITIA 11/11/04 TEST TERMIN PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COND. EMIS. COND. EMIS. COMPLETE? COMPLETE. COMPLETE	ACCUM NATION DATE ACCUM NATION DATE OPERA T DESCRIPTION Z THERMAL PRESSURE: C1 NO OF CYCLES I ISOLATION MAGNETICS LIST PFR NOS. LIST PFR NOS. SUMMARY FOR ACTIONS	VACUUM TEMPERATU DE-5 C VIC IN TEMP. LEVEL ("C) AND ACC HOT: "C, HOT:	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER DUMULATED DURATION (HRS.) h COLD: "cc, h cc, h
HARDWARE HAS SUCCESSFULLY COMPLETED THE ENVIRONMENTAL TESTS LISTED ON THIS FORM OR REMAINING ACTIONS HAVE BEEN TAKEN, INCLUDING RE SOCIETA OF THE PROPERTY OF	PL Building 144 ERIAL NUMBERS ACTUALLY TESTED SAL 12 415 VIBRATION ACOUSTIC AXES: X Y Z NE VIBRATION COND. SUSC. ERE THERE ANY PFRS GENERATED DURING ENVIR YES NO (IF NO, ATTACH E RE THE POST ENVIRONMENTAL DAMAGE INSPECTIVE YES NO (IF NO, ATTACH E PER ALL PLANNED TESTS/LEVELS/DURATIONS ACH YES NO (IF NO, ATTACH E TESTS HAVE NOT BEEN SUCCESSFULLY COMPLI	TEST DATES) TEST INITIA 11/11/04 TEST TERMIN PYROSHOCK SHOCK AXES: X Y SHOCKS/AXIS: COND. EMIS. COND. EMIS. COMPLETE? COMPLETE. COMPLETE	ACCUM NATION DATE ACCUM NATION DATE OPERA T DESCRIPTION Z THERMAL PRESSURE: C1 NO OF CYCLES I ISOLATION MAGNETICS LIST PFR NOS. LIST PFR NOS. SUMMARY FOR ACTIONS	VACUUM TEMPERATU DE-5 C VIC IN TEMP. LEVEL ("C) AND ACC HOT: "C, HOT:	RIOR TO FIRST ENVIRONMENTAL TEST IMENTAL EXPOSURE RE ATMOSPHERE OTHER DUMULATED DURATION (HRS.) h COLD: "Cc, h h COLD: "Cc, h

Attachment of HRCR Item #7: ETAS (environmental test summary) ETAS No. HS 037 (continued)

PAGE 1 JPL 2683 R 1/96 FF **ENVIRONMENTAL TEST AUTHORIZATION AND SUMMARY (ETAS)** OTHER AUTHORIZATION PROVISIONS AND EXPLANATIONS $2 \ \omega \ 3$ vacuum thermal cycles will also be completed. 3-axis vibe was completed and is carried on AIDS#'s 243946 and 244164, ETAS#'s HSO31 nad HSO32. PAGE 2 JPL 2683 R 1/98 FF

Attachment of HRCR Item #7: ETAS (environmental test summary) ETAS No. HS 037 (continued

(·	COMMENTS	
r (ETAS)	PASS/ FAIL	
D SUMMARY Mary	TEST	
FAL TES THORIZATION AND SUMMARY (ETAS) ENVIRONMENTAL TEST SUMMARY	DATE TEST PERFORMED	
ENVIRONMENTAL TES THE STATES THE	TEST ENVIRONMENT LEVELS & DURATION	cycles. <10E-5 mbar, <70K tv RT.
ENVIB	ETAS	HSO37
	N/S	5
4	HARDWARE	SPIRE JFET (10209750-1)

Attachment of HRCR Item #7: ETAS (environmental test summary) ETAS No. HS 031

ENVIRONMENTAL TEST AUTHORIZATION AND SUMMARY (ETAS) **AUTHORIZATION SECTION** PROJECT HS031 Herschel TEM/ASSEMBLY TITLE DATE ISSUED JFET Modules S/N 12.13 9/29/04 REFERENCE DESIGNATION NUMBER PART NO. (IF MULTIPLE, ATTACH LIST) REV. SERIAL NO. 10209750-1 012,013 HARDWARE TYPE PRE-ENVIRONMENTAL INSPECTION REPORT NUMBER (ATTACH IR) EM QUAL ☑ FLIGHT FLIGHT SPARE OTHER WIRING HARNESS SERIAL NO. ☐ EM ☐ SE ☐ EM QUAL ☐ FLIGHT TEST DESCRIPTION (CHECK ALL APPLICABLE) TYPE OF TEST ☐ ACOUSTIC ☐ EMC SINE VIBRATION ☐ PYROSHOCK OTHER ☐ QUALIFICATION ☐ FLIGHT ACCEPTANCE RANDOM VIBRATION THERMAL VAC. THERMAL ATMOSPHERE PROTO FLIGHT RETEST WILL ALL TESTS/LEVES/DURATIONS REQUIRED BY THE PROJECT DOCUMENTS BE PERFORMED ON THIS UNIT? NO (IF NO, ATTACH EXCEPTIONS LIST) ENTER PROJ. DOC. NO. AND REV. HAS THE UNIT PASSED ALL PRE-ENVIRONMENTAL FUNCTIONAL TESTS? BRIEF EXPLANATION X YES NO (IF NO, ATTACH EXCEPTIONS LIST) HAVE ALL DESIGN ANALYSES BEEN COMPLETED AND REQUIRED CHANGES BEEN IMPLEMENTED? NO (IF NO, ATTACH EXCEPTIONS LIST) BRIEF EXPLANATION IS THE TEST ARTICLE IDENTICAL TO OTHER FLIGHT UNITS? BRIEF EXPLANATION Stiffeners have been added to the design and included in this unit ☐ YES NO (IF NO, ATTACH EXCEPTIONS LIST) ARE ALL PFRs AGAINST THIS UNIT CLOSED? BRIEF EXPLANATION PFR's in process of closure. All issues have been addressed and qualified. NO (IF NO, ATTACH EXCEPTIONS LIST) HAVE ALL WAIVERS AND ECRIS BEEN APPROVED AND ARE THEY INCORPORATED? BRIEF EXPLANATION NO (IF NO, ATTACH EXCEPTIONS LIST) **TEST AUTHORIZED BY** COGNIZANT ENGINE MGR/INSTR MRG/PI PREP REP Martin Hen SUMMARY SECTION TEST AGENCY (IF MULTIPLE, ATTACH SUMMARY AND TEST DATES) TEST INITIATION DATE ACCUMULATED OPERATING HOURS PRIOR TO FIRST ENVIRONMENTAL TEST JPL Building 144 9/29/04 SERIAL NUMBERS ACTUALLY TESTED TEST TERMINATION DATE OPERATING HOURS DURING ENVIRONMENTAL EXPOSURE 0/29/04 S/W 12, 13 TEST DESCRIPTION THERMAL VACUUM VIBRATION ACOUSTIC PYROSHOCK SHOCK TEMPERATURE ATMOSPHERE AXES: X Y AXES: X PRESSURE: <10E-5 NIA SINE VIBRATION NO OF CYCLES: 2 cm # cm3 NO OF CYCLES: RANDOM VIBRATION X X X SHOCKS/AXIS: TEMP, LEVEL (°c) AND ACCUMULATED DURATION (HRS.) COND. EMIS. ☐ ISOLATION EMC COND. SUSC. COLD: ESD RAD. SUSC. RAD. EMIS. ☐ MAGNETICS WERE THERE ANY PFRs GENERATED DURING ENVIRONMENTAL TESTS? LIST PER NOS / BRIEF EXPLANATION NO (IF NO, ATTACH EXCEPTIONS LIST) ARE THE POST ENVIRONMENTAL DAMAGE INSPECTIONS COMPLETE? LIST PER NOS. / BRIEF EXPLANATION NO (IF YES, ATTACH A COPY OF THE INSPECTION REPORTS. IF NO, ATTACH EXPLANATION) WERE ALL PLANNED TESTS/LEVELS/DURATIONS ACHIEVED? LIST PFR NOS. / BRIEF EXPLANATION NO (IF NO, ATTACH EXCEPTIONS LIST) TESTS HAVE NOT BEEN SUCCESSFULLY COMPLETED. SEE THE ATTACHED SUMMARY FOR ACTIONS THAT NEED TO BE TAKEN. DATE | TECHNICAL MGR./INSTR MRG./PI PREP REP ENVIRONMENTAL REQUIREMENTS ENG. DATE COGNIZANT ENGINEER DATE HARDWARE HAS SUCCESSFULLY COMPLETED THE ENVIRONMENTAL TESTS LISTED ON THIS FORM OR REMAINING ACTIONS HAVE BEEN TAKEN, INCLUDING RETEST. DATE DATE | TECHNICAL MGR./INSTR MRG./PI PREP REP DATE ENVIRONMENTAL REQUIREMENTS ENG. COGNIZANT ENGINEER 217105 W 2-7-05 PAGE 1 JPL 2683 R 1/98 FF

Attachment of HRCR Item #7: ETAS (environmental test summary) ETAS No. HS 031 (continued)



ENVIRONMENTAL TEST AUTHORIZATION AND SUMMARY (ETAS)

OTHER AUTHORIZATION PROVISIONS AND EXPLANATIONS

is a 3-axis warm vibration test (room temp) done on the JFET flight modules SN012 and 013. The test will be done with the JFET unit mounted inside a mock-up JFET rack. The unit will be assessed both before and after the test with visual inspections and electrical checkouts. 3 response accelerometers will be mounted onto the JFET rack in order to give response data.

2 to 3 vacuum thermal cycles will also be completed.

FFR 284742- judged to not be due to shake test (Rework) planned)
Thermal not performed - later performed (2TAS H5037 for S/N 12)
ETAS (45035)

Shake successfull for both.

PAGE 2 JPL 2683 R 1/98 FF

Attachment of HRCR Item #7: ETAS (environmental test summary) ETAS No. HS 031 (continued)

9 11 1		ETTIS TOO TIS OFT (CONTINUES)	1
(COMMENTS		PAGE 3 JPL 2683 R 1/86 FF
Y (ETAS)	PASS/ FAIL		
ID SUMMAR) Mary	TEST		
'AL TES JTHORIZATION AND SUMMARY (ETAS) ENVIRONMENTAL TEST SUMMARY	DATE TEST PERFORMED		
ENVIRONMENTAL TES JTH ENVIRONMENT	TEST ENVIRONMENT LEVELS & DURATION	X, Y, and Z I minute Random Vibe Frequency [Hz] 20 0.01 100 0.05 300 0.0214 500 0.0214	
ENVII	ETAS	HSO31	
	N/S	012,	
	HARDWARE	SPIRE JFET (10209750-1)	

Attachment of HRCR Item # 8: Test Data - Source Voltage & Noise For Module 12

JFET SOURCE VOLTAGE MEASUREMENT

Post Vibe, post bake, SN12,15 module, grn dewar, rm T. PERF TEST Post Vibe, post bake, SN12,15 module, grn dewar, Helium, , plate Rm T Rm T Rm T 4K -1.5 1.1345 0.959 1.2181 0.9258 1.0223 1.0269 0.9839 1.1327 0.9608 1.1088 Channel # 1.002 0.973 0.97 1 125 0.691 0.64 0.685 0.829 0.003 0.003 0.001 0.002 0.007 0.004 0.001 0.003 0.976 0.684 0.999 0.64 0.826 0.746 0.729 0.74 0.434 2 0.002 0.009 0.001 0.005 0.005 0.006 0.004 0.006 1.196 0.72 0.93 0.90 3 0.005 0.008 0.003 0.005 0.007 0.003 0.981 0.894 0.662 0.64 0.59 0.849 0.852 4 0.001 0.003 0.005 0 0 0.005 0.004 0.003 0.97 1.149 0.64 0.616 5 0.009 0.012 0.005 0.007 0.002 0.014 800.0 0.974 1.46 0.002 0.001 0 6 0.013 0.013 0.011 0.014 0 0.96 0.99 0.65 0.974 1.34 1.108 0.808 0.007 0.003 0.007 0.004 0.004 0.001 0.006 0.003 0.64 0.68 0.68 0.63 0.69 0.66 0.66 0.805 0.509 0.515 0.820 8 0.001 0.002 0.004 0.005 0.002 0.007 0.003 0.006 0.999 0.825 0.558 1.415 0.992 9 0.007 0.007 0.005 0.001 0.003 0.003 0.006 0.008 10 0.973 1.058 0.981 1.314 0.649 0.72 0.68 1.020 0.001 0.003 0.005 0.002 0.001 0.002 0.003 0.63 0.65 0.969 0.970 0.85 0.16 11 0.003 0.012 0.002 0.002 0.005 0.012 0.001 0.001 0.639 12 0.002 0.009 0.007 0.003 0.003 0.009 0.006 0.004 0.947 13 0.003 0.002 0.009 0 0.004 0.008 0 0.003 0.974 0.656 0.93 0.001 14 0.002 0.003 0.004 0.003 0.003 0.002 0.006 0.963 1.064 0.986 0.929 0.62 0.75 0.67 1.307 0.993 0.87 0.519 15 0.015 0.847 0.002 0.01 0.61 0.002 0.005 0.003 0.004 16 0.006 0.01 0.012 0.001 0.004 0.01 0.012 0.001 1.540 1 114 1.246 0.434 0.804 0.80 0.99 0.67 17 0.003 0.005 0.002 0.003 0.007 0.006 0.001 0.007 0.988 1.067 1.064 1.144 0.81 0.679 0.646 0.641 0.619 0.961 1.146 0.003 0.001 0.001 0.006 0.005 0.001 0.005 0.006 0.003 0.001 800.0 0.003 0.001 0.003 800.0 0.498 0.001 0.003 0.004 0.003 0.003 0.649 1.071 1.071 0.01 0.001 0.006 1.256 0.71 1.044 0.97 0.743 0.001 0.001 0.004 0.002 0.743 1.02 1.66 1.043 1.37 0.97 0.963 0.694 0.63 23 0.001 0.003 0.002

0.981

0.668

0.769

0.011

0.670

0.004

1.706

0.011

0.001

24

1.058

Attachment of HRCR Item #8: Test Data - Source Voltage & Noise

Board S/N 022 in Module S/N 012

	Pwr1	Pwr2	Pwr3	Pwr4	Pwr5	Pwr5b	Pwr7
Vdd (V)	2.8	2.8	2.8	2.8	2.8	2.8	2.6
Vss (V)	-1.7	-1.8	-1.9	-1.85	-1.75	-1.6	-1.5
Vdd' (V)	2.518	2.507	2.495	2.501	2.512	2.53	2.342
Vss' (V)	-1.424	-1.513	-1.602	-1.557	-1.469	-1.336	-1.248
ldd (mA)	1.081	1.0867	1.1682	1.1462	1.1025	1.0372	0.989
Iss (mA)	1.0433	1.1243	1.13	1.1086	1.0651	0.9997	0.9524
I (mA)	1.06215	1.1055	1.1491	1.1274	1.0838	1.01845	0.9707
P (mW)	4.1869953	4.44411	4.7078627	4.5749892	4.3146078	3.9373277	3.484813

Channel Num			Vn @150 Hz				
Channel: 1	8.57	9.36	9.53	12.68	13.99	13.85	9.18
Channel: 2	9.51	6.81	7.30	7.18	8.20	11.35	9.73
Channel: 3	19.83	11.28	8.52	10.28	14.21	26.98	41.15
Channel: 4	6.77	6.81	6.21	6.34	5.60	6.82	9.20
Channel: 5	22.33	12.03	7.79	9.72	13.01	42.45	114.55
Channel: 6	8.96	7.67	6.76	6.77	8.01	11.42	32.56
Channel: 7	20.07	10.52	7.67	9.79	16.12	33.08	29.73
Channel: 8	7.36	6.44	7.15	7.85	8.18	6.83	10.72
Channel: 9	6.48	5.90	6.69	6.11	5.50	6.52	7.74
Channel: 10	28.92	17.89	12.86	12.95	23.85	42.74	36.60
Channel: 11	13.87	10.30	5.25	8.30	11.77	20.68	53.01
Channel: 12	9.96	6.67	6.04	5.32	7.00	15.35	59.17
Channel: 13	6.19	6.32	4.73	8.26	5.34	8.25	13.20
Channel: 14	6.97	6.07	6.34	8.54	7.58	8.98	12.65
Channel: 15	6.55		6.17	9.06	7.07	9.54	19.05
Channel: 16	6.98	6.21	5.76	6.64	6.57	9.00	19.42
Channel: 17	7.13	6.92	9.56	8.44	8.07	6.93	8.87
Channel: 18	11.86	11.82	11.66	10.16	11.61	11.84	12.27
Channel: 19	8.10	8.25	7.70	8.61	9.47	10.81	11.24
Channel: 20	8.78	6.20	5.55	7.89	6.28	9.01	21.35
Channel: 21	6.79	7.81	7.84	8.92	7.46	6.75	
Channel: 22	7.36	7.26	6.92	7.63	7.00	7.52	8.21
Channel: 23	4.87	5.87	5.05	4.95	6.65	6.19	6.79
Channel: 24	7.69		7.84	7.67	7.31	6.51	8.26
Median	7.90	6.88	7.03	8.28	7.79	9.27	12.46
Overall Mean	10.50	8.24	7.37	8.34	9.41	14.14	23.53
Good Mean	8.04	7.82	7.37	8.34	8.45	8.78	9.86
MP Reqd					15		
Yield	0.83		1.00	1.00	0.92	0.75	0.58
# Good Ch.	20	23	24	24	22	18	14
# Bad Ch.	4	1	0	0	2	6	10

JFET_Mod12_brd22_Noise_perf.xls

Attachment of HRCR Item #8: Test Data - Source Voltage & Noise

Board S/N 023 in Module S/N 012

	Pwr1	Pwr2	Pwr3	Pwr4	Pwr5	Pwr5b	Pwr7	Pwr8
Vdd (V)	2.8	2.9	2.8	2.8	2.8	2.8	2.8	2.7
Vss (V)	-1.8	-1.8	-1.7	-1.6	-1.65	-1.67	-1.63	-1.5
Vdd' (V)	2.518	2.618	2.528	2.538	2.533	2.531	2.534	2.449
Vss' (V)	-1.524	-1.524	-1.435	-1.346	-1.39	-1.408	-1.372	-1.256
Idd (mA)	1.0838	1.0858	1.0441	1.0042	1.0239	1.0321	1.0159	0.9612
Iss (mA)	1.0412	1.0424	1.0015	0.9616	0.9616	0.9894	0.9737	0.9194
I (mA)	1.0625	1.0641	1.0228	0.9829	0.99275	1.01075	0.9948	0.9403
P (mW)	4.294625	4.4075022	4.0533564	3.8175836	3.89455825	3.98134425	3.8856888	3.4838115

Channel Num					Vn @150 Hz		Vn @150 Hz	Vn @150 Hz
Channel: 1	19.12	14.42	29.49	45.15	41.92	35.94	41.83	32.91
Channel: 2	5.83	6.25	8.03	7.79	7.93	7.49	6.59	14.62
Channel: 3	6.57	6.77	6.51	7.27	7.20	6.62	9.78	10.17
Channel: 4	6.56	7.37	5.74	6.10	7.36	6.08	11.15	10.07
Channel: 5	6.07	6.57	7.14	6.43	7.02	7.28	6.90	13.64
Channel: 6	6.71	7.44	9.86	15.05	11.64	10.91	12.18	21.26
Channel: 7	7.46	5.14	7.82	17.07	10.75	9.85	11.64	34.13
Channel: 8	10.68	9.40	18.46	24.54	23.36	16.82	22.53	43.50
Channel: 9	10.13	9.40	11.29	12.05	10.98	9.86	10.89	17.80
Channel: 10	7.90	8.48	9.94	13.88	11.51	10.69	13.68	19.58
Channel: 11	6.69	6.70	9.76	10.44	11.27	10.02	13.26	14.20
Channel: 12	7.29	6.29	8.42	13.86	12.83	9.97	11.01	31.14
Channel: 13	8.60	9.13	10.12	15.91	15.41	12.54	15.88	45.31
Channel: 14	11.62	13.09	13.13	17.24	13.69	13.36	15.65	34.14
Channel: 15	9.60	10.50	10.99	15.48	13.01	12.06	14.49	27.44
Channel: 16	6.36	8.04	7.08	9.24	7.01	6.50	7.86	19.30
Channel: 17	6.60	7.16	8.47	9.27	8.52	8.75	10.15	16.73
Channel: 18	7.38	7.02	6.30	6.12	6.79		6.87	7.59
Channel: 19	7.47	7.36	5.76	9.32	8.14	8.51	9.67	20.16
Channel: 20	7.43	11.84	9.04	14.93	10.78		14.09	35.81
Channel: 21	7.25	8.48	6.26	8.42	8.05	7.26	7.89	12.68
Channel: 22	5.99	6.83	6.76	10.30	7.99	7.89	7.70	25.83
Channel: 23	6.51	6.05	7.20	10.61	6.28	7.45	7.56	16.32
Channel: 24	6.71	7.79	8.75	14.80	10.96	9.80	11.98	28.14
Median	7.27	7.41	8.44	11.33	10.76	9.82	11.08	19.87
Overall Mean	8.02	8.23	9.68	13.39	11.68	10.62	12.55	23.02
Good Mean	7.54	8.23	8.38	10.05	9.51	9.19	10.27	11.85
MP Reqd					15			
Yield	0.96	1.00	0.92	0.71	0.88	0.92	0.83	0.29
# Good Ch.	23	24	22	17	21	22	20	7
# Bad Ch.	1	0	2	7	3	2	4	17

JFET_Mod12_brd23_Noise_perf.xls

Attachment of HRCR Item # 9: SPIRE MIUL Cover Page

MIUL = Material Identification & Utilization List

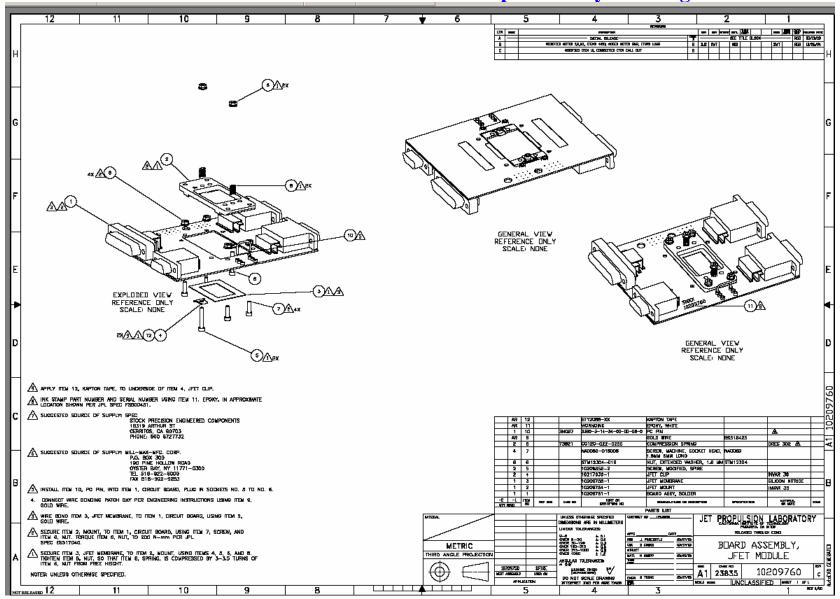
Declared Materials List's and Processes List are not included in this HRCR

	Mater	rials and Processes	s List	
		SPIRE		
		JPL D-25725		
		REV B 1/05/04		
for use exclusive	ely on the Herschel/P and shall not be re-tra	lanck projects. The	d is being transferred information may not be ed to any other party v SA.	e used for any
	Reviewed by:	MIDA	ny	
	M.	Knopp M&P Engine	er	

Attachment of HRCR Item #11:

See End of This HRCR Package for "JFET Module Handling Document"

Attachment of HRCR Item # 14: JFET Module Top Assembly Drawing 10209750-1



Attachment of HRCR Item #23: Qualification Compliance Test

Qualification Model JFET Module

		EID	P Coverpage	For JFET Te	sting		
Unit Identfication						1	
Name	T-	JEET O	M Module				
Part #	-		9750-1				
S/N	-		001				
5/14	-	77	001				
Environmemtal Testing							
	Π	Axes		Duration/# of			
	┖	Tested	Temperature	Cycle	Requirement	Source	Waiver
						SSSD,	
Random Vibration Test	╄	X, Y, Z	100 K	2 min/axis	X, Y, Z	JFET-DES-07	
l						SSSD,	HR-SP-JP
High Level Sine Vibe Test	⊢	None	NA	NA	X, Y, Z	JFET-DES-07	RFW_005
Bakeout	╄	NA	80 C	72 Hours	80C, 72 Hrs	D-20549	
Thermal Cycles		NA	RmT to 80 K	27	Minimum 15	D-20549	
Performance Characteristics	;						
	Т		Specif	ication	s	ource	Waiver
Power needed for <11 bad	T			or CQM.		SSD.	RFW in
channels (Min Perf.)		9.1 mW		PFM/FS	· -	550, 5, JFET-PER-02	process
Power needed for <4 bad	\vdash	e. i ilivv		or CQM.		SSD.	process
channels (Design Value)		10.8 mW		PFM/FS	I -	5, JFET-PER-02	
Power needed for 100 %	T	10.0 1111	7 11177 101		0.2200	0,012112102	
Yield per unit		13.5 mW	l N	A		NA	
Median Noise at < 11 bad chs.	T	7.13 nV/rtHz			SSSD. J	FET-PER-01	
Median Noise at < 4 bad chs.	T	6.1 nV/rtHz	Min	<7 nV/rtHz		FET-PER-01	
Median Noise at 100 % Yield.	\vdash	6.97 nV/rtHz		Design Value		FET-PER-01	
# of Channels over the	\vdash		< 15 mV for C0			SSSD.	
max. offset voltage		0	< 15 mV for PF	M/FS		BDA-DRCU-27	
	П					SSSD,	
Common Mode Rejection Ratio		< -60 dB by d	esign, as meas	ured in EM4 un	it	BDA-DRCU-11	
Board Level Detail							
		Board	SN 001			Source	
# Channels Tested	:	24					
						SSSD,	
Median Noise at 3.5 mW	:	18 n	V/rtHz			JFET-PER-01	
# of good channels				1		SSSD,	
at 3.5 mW	:	7	29% Yield	_		JFET-PER-02	
Power Needed for		0.75 14				SSSD,	
100 % Yield Median Noise at High Power (w/	:	6.75 mW		-		JFET-PER-02 SSSD.	
100 % Yield)		8.07	nV/rtHz			JFET-PER-01	
Median Gain at High Power	+		.98	-		NA	
mestali cali at riigii i owei	+	, ·	.00	 		150	
	+					L	
Definitions	۲			I		I	
Good Channels		Noise loss than	a min. performar	l see value of 15 ml	//etill=	I .	1
Yield		# of Good Char		ice value or 10 h	инп4		
Filenames	-	or Good Char	iiieis / 24			1	
	+	OwellECTO: "	Chablaine Com				
Noise Measurements	H	Qualife i Post	/ibeNoise_Summ	ary.pur			
Notes	+						
The Base temperature for all performa	l nno-	obarastorization	n was AV				
All Noise Measurements were made v	vitri	the inputs shorte	ea to grouna				+

Attachment of HRCR Item # 24 & #25: Mate/Demate & Operation Logs

	TEET	5/N 12	15				A Company of the Comp
Date	Time	AIDS	Power	Mate	Demate	Transport	Notes
1/5/04		244299		×			103 -> 183
11/5/04		~	X			X	
1/5/04	1.	~					s he each boad, wem s.V.
19/04		1					transfer LN2 (77K)
1/9/04		~					transfer holion (4K)
							Transfer voiting ()
1/9/04			×				4 hours, bond 74, mise data
1/10/04			×				8 hrs " "
/11/04		-1	×				1 45 11 11
1/11/04		C ()	×				8 hrs , board 35, noise data
1/12/04		-	×	-			2 hrs, wood 34, gain duta, CMR
112104			×				3 ks, board 35, gain, CMRR
112/04			57 55				begin warm up
116/04		cr		k	× ×		switch connector to fix goob w/ SNIA
/16/04	· ·						eve out
117104							go to LNZ helium
119/04		α .	×				Prob fixed (GSE).
(19/04		(1)	×				6 hrs , board 22 , noise data
122104	· · · · · · · · · · · · · · · · · · ·	C	x				2 hs, bond 22, noise data
122104		~	X				6 hrs, brand 23, poised data
123 104		"	x				2 hr re a
123 /04			×				3 WS , a , gain, CMPR
123/04		· (-	χ.		:: :		3 ks, bood 22 gain, CMRC
130/04		"	x				. 5 hrs each board, wom s.V.
11/04					*	*	183→ 103
				·. ·			

Attachment of HRCR Item # 24 & #25: Mate/Demate & Operation Logs (continued)

Date	Time	AIDS	Power	Mate	Demate	Transport	Notes
			-				
9/24		243900				Х	103 -> 158
9124	11 1	243900					fring art, bring to 80°C
9/26							back to on temp, pressure
9/26	:					X	158 -> 183
					-		
9/28		243946	×	X	*		take previbe worm S.V. measurement
1/29		"				×	183-144
9/29		"					from out trice (X,Y,+ton Z)
9129						×	144 -> 183
					a		
#5010/11			泵	X			install into gra down, son 3.0
10/11			×				war s.v., she each bond
10/11					×	×	183 - 103 (problem with S/N13)
				:			PFR 285374
			: .				
				-			
				- 1 ₄			
			•				

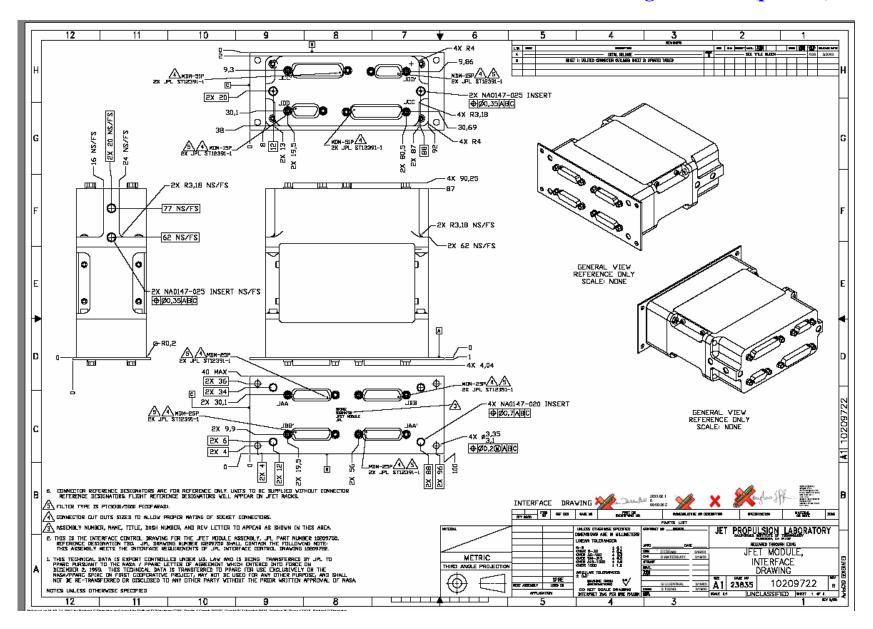
Attachment of HRCR Items # 24 & # 25: Mate/Demate & Operation Logs (PWB S/N 22)

5-3-4 1:20PM NAW 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	DATE	S/N: O22	S/N OREFATOR	PWR ON			MA	JCC	JDD	JAA	DEN JBB	JCC	JDD	TRANSFORT	NOTE
103-4 7.30 AM NON 1-19-4 NIN 1-5-4 NAN 1-30-4 NAN 1-20-4 NAN 1-15-4 NIN 1-15-4 NIN 1-15-4 NIN 1-15-4 NIN 1-15-4 ST NI		1:20PM	Nho			1	(I	1	1	1	1	1	111/11/01 0111	SAVER ON- & DEMOTE
-19-4 NIN ANN 11 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		7:50 AM				1	1	1	1	/		-	/		
1-30-4 NAN 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1			NM			/	/	/	/						
1-30-4 NM 1			NAN,						/			-	/		
1-20-4 NM 1 1 1 SOURCE -15-4 NM 1 1 1 SOURCE -6-4 NM V V V V V V V SOURCE -15-4 ST NM V V V V V V SOURCE TEST -16-4 ST NM V V V V V GND S CHASSIS -22-4 ST NM V V V V V V GND S CHASSIS -22-4 ST NM V V V V V SOURCE TOST -23-4 ST NM V V V V V CONDS CHASSIS						/	/		/		/	1	/		
-15-4 NAN					1				/			-	1		
1-15-9 NAN															OND & OHASSIS
-16-4 5T NOW V V GND 3 CHASSIS 1-22-4 5T NOW V V V COD SOURCE TOST -23-4 5T NOW V V V V COD SOURCE TOST -23-4 5T NOW V V V V COD COND \$ CHASSIS				_1_	1	100									SAURCE
-16-4 5T NOW V V GND 3 CHASSIS 1-22-4 5T NOW V V V COD SOURCE TOST -23-4 5T NOW V V V V COD SOURCE TOST -23-4 5T NOW V V V V COD COND \$ CHASSIS								-		V	1	/	/		DEMATE SAVERS M
-22-4 FT NIN V V V V V SOURCE TOST -23-4 ST NAN V V V V V CAND & CHASSIS				_ 0	d	V	V		V			r	V	2	SDUPCE TEST
-22-4 FT NIN V V V V V SOURCE TOST -23-4 ST NAN V V V V V CAND & CHASSIS	-16-4		ST NAV					V	V						GND & CHARSOS
-22-4 ST NIN V C V V V SOUPCE TEST -23-4 ST NAN V C V V CAND & CHASSIS	-22-4					r	i.	V	V			V	V		GNDS CHASENS
-23-4 ST NAV V C V V CTNP & CHASSIS	-22-4		ST KIN		U			r		v	1				SOUPCE TEST
SOUPLE TEST	-23-4		ST NOW			V	c					0	V		CAND & CHASSIS
	-23-4		ST. NAW					V	V	V	V				SOURCE TEST
		7													
					-										
												,			
				14											

Attachment of HRCR Items # 24 & # 25: Mate/Demate & Operation Logs (PWB S/N 023)

VICE(BRD	S/N) 023	(37)	PROJEC	T: SPIRI	SE THE	BOAF	<u>F. COI</u>	LUIVIN	IO DE	SCHIBE	= ACTIO	ONS		
DATE	TIME	S/N OPEPADE	PWR ON	PWR OFF	The same of the sa	MA	TE	IDD		DEN				NOTE
-9-4	1:20 PM	NM	ON.	UFF	JAA	JBB	JCC	JDD	JAA	JBB	JCC	JDD	TRANSFORT	
	7:30 AM	MAN		-	-	5-1-				-				SHIER ON
119/04	1.30 400	NAW	-		_		-1							U GND9 CHASSIS
5-04		NAM	-										-	- 10 d
5-04		WAN	/	~										GND9 OWASSIS - STUBR ON
15-04														SOURCE TEST 11
		MIN				-					-			GND 9 CHACUS - "
15-04		NEW							./	V				SOUPCE TEST "
15-04	135				V	0	-	V	V	-	V	V		DE MATE SAVERS MAT
		STENNE	V	V	V	0	~	0			V	V		GND of CHASEIS
16-04	,	ST NOW	V	V				-	V	~		-		SOURCE TEST
22.04		ST NAV			V	V	c				V	~		AND & CHASH
		51 1010					V	V	V	0				SOUPER TEST
23-04		ST NN			V	V	1	_		-	~	-		GND& CHASSIS
							V	V	V	V				SOURCE TEST
			- 3											(
			130											
				. 1										
	The Many			11/10/1										
											-			
	-	-								227 - 11 (
							-							

Attachment of HRCR Item # 26: MICD - JFET Interface Drawing 10209722 (p 1 of 2)



Attachment of HRCR Item # 26: MICD - JFET Interface Drawing 10209722 (p 2 of 2)

										_	
╽┌╴	12 11	10 9	8	7 ★	6		5	4_	3	2	
	JAA JEET DUTPUT 139	JAM JEET OUTPUT ZA		JCC JFET IMPUT 1			JOD JEET SERVICE 1		JCC' JFET INPUT 2		
ll	PIN # PIN PURPLISE	PIN # PIN PURPUSE 1 SIGNAL H+1	PIN			TN #	PIN PURPOSE	4	PIN # PIN PURPOS	E	
H	1 SIGNAL M+	1 ZIGNAL N+'	L	BIAS V+			Vss	4	1 BIAS V+'		ļ
	2 SIGNAL N+	3 SIGNAL P+1	2	BIAS V-		\rightarrow	V+	-	5 BIAS A-1		
	3 SIGNAL P+ 4 SIGNAL R+	4 SIGNAL R+1	3	SIGNAL Y+	\dashv		H+ V-	-	3 SIGNAL Y+' 4 SIGNAL V-'		
Н	5 SIGNAL S+	5 SIGNAL S+'	5	SIGNAL V+	\dashv		V-	-	5 SIGNAL V+'		
	6 SIGNAL T+	6 SIGNAL T+1	6	SIGNAL T+	\dashv \vdash		H+	┨	6 SIGNAL T+		
	7 SIGNAL U-	7 SIGNAL U-1	7	SIGNAL S-	\dashv		V+	┨	7 SIGNAL S-		
G	8 SIGNAL V-	B SIGNAL V→	<u> </u>	SIGNAL P+	\dashv	\rightarrow	Vss	┨	B SIGNAL P+		lo
	9 SIGNAL V-	9 SIGNAL W-	9	SIGNAL N-	\dashv \vdash		BIAS GND	┨	9 SIGNAL N-/		
	10 SIGNAL X-	10 SIGNAL X-	10	SIGNAL L-		$\overline{}$	Vald	1	10 SIGNAL L-/		
	II SIGNAL Y-	11 SIGNAL Y-'	11	SIGNAL K+			H-	1	1L SIGNAL K+		
П	12 SIGNAL Z-	12 SIGNAL Z-'	12	SIGNAL I-	\neg	12	CHASSIS GND	1	12 SIGNAL I-		
	13 FPU GND	13 FPU GND'	13	SIGNAL H+	_	13	H-	1	13 SIGNAL H+		
	14 SIGNAL M-	14 SIGNAL H-'	14	SIGNAL F+			Volai	1	14 SIGNAL F+*		
F	13 SIGNAL N-	15 SIGNAL N-'	15	SIGNAL E-		15	BIAS GND]	15 SIGNAL E-		l.
	16 SIGNAL P-	16 SIGNAL P-'	16	SIGNAL C+				1	16 SIGNAL C+*		
	17 SIGNAL R-	17 SIGNAL R-'	17	SIGNAL B-			JUDY JEET SERVICE 2	4	17 SIGNAL B-		
	18 SIGNAL S-	18 SIGNAL S-'	18	SIGNAL A-	_ I	IN #	PIN PURPOSE	-	18 SIGNAL A-		
П	19 SIGNAL T-	19 SIGNAL T-'	19	BIAS GND			Vss'	4	19 BIAS GND'		
	20 SIGNAL U+	20 SIGNAL U+'	20	SIGNAL Z+	⊢	$\overline{}$	V+'	-	20 SIGNAL Z+'		
	21 SIGNAL V+	21 SIGNAL V+'	21	SIGNAL X-	⊢		H+'	-	21 SIGNAL X-		
F	22 SIGNAL W+	22 SIGNAL V+'	22		— ⊢	_	V→	-	22 SIGNAL W+'		l _i
-	23 SIGNAL X+	23 SIGNAL X+'	23	SIGNAL U-	⊢		H+'	-	23 SIGNAL U-		
	24 SIGNAL Y+	24 SIGNAL Y+'	24	SIGNAL T-	⊢	$\overline{}$	A+,	-	24 SIGNAL T-		
1.1	25 SIGNAL Z+	25 SIGNAL Z+'	25	SIGNAL R+		$\overline{}$	Vsc'	-	25 SIGNAL R+		
P	JEE JFET DUTPUT 1A	JDB JFET DUTPUT 20	26	SIGNAL P-	— ⊢	$\overline{}$	BIAS GND	-	26 SIGNAL P-		!
	PIN # PEN PURPOSE	PIN # PIN PURPOSE	27	SIGNAL M+		$\overline{}$	Vold'	1	27 SIGNAL M+		
	1 SIGNAL A+	1 SIGNAL A+'	28	SIGNAL L+		$\overline{}$	H-'	┨	28 SIGNAL L+		
n	2 SIGNAL B+	2 SIGNAL II+'	29	SIGNAL J-		$\overline{}$	CHASSIS GNII'	┨	29 SIGNAL J		l,
	3 SIGNAL C+	3 SIGNAL C+1	30	SIGNAL I+		$\overline{}$	H-1	┨	3D SIGNAL I+'		ا
	4 SIGNAL D+	4 SIGNAL II+'	31	SIGNAL G-		$\overline{}$	Yakair	1	31 SIGNAL G-		
	5 SIGNAL E+	5 SIGNAL E+'	322	SIGNAL F- SIGNAL D+		$\overline{}$	BIAS GND	1	32 SIGNAL F-/ 33 SIGNAL II+/		
Н	6 SIGNAL F+	6 SIGNAL F+'	33	SIGNAL U+				_	33 SIGNAL II+/ 34 SIGNAL C-/		l,
	7 SIGNAL G-	7 SIGNAL 5-1	36						35 SIGNAL A+		į.
	6 SIGNAL H-	B SIGNAL H-'	36		_				36 SIGNAL X-/		ľ
	9 SIGNAL I-	9 SIGNAL 1-'	37	SIGNAL Y-	_				37 SIGNAL Y-		
~	10 SIGNAL J-	10 SIGNAL J-	36	SIGNAL X+					38 SIGNAL X+		į
	II SIGNAL K-	11 SIGNAL K-'	39	SIGNAL V-	-				39 SIGNAL V-'		
	12 SIGNAL L-	12 SIGNAL L-'	4D						4D SIGNAL U+*		
Н	13 FPU GND	13 FPU GND	41	SIGNAL S+					41 SIGNAL S+		<u> </u>
	14 SIGNAL A-	14 SIGNAL A-'	42						42 SIGNAL R-1		
	15 SIGNAL B-	15 SIGNAL B-'	43	SIGNAL N+					43 \$1GNAL N+*		
B	16 SIGNAL C-	16 SIGNAL C-'	44	SIGNAL M-					44 SIGNAL M-		Į.
	17 SIGNAL D-	17 SIGNAL II-	45	SIGNAL K-					45 SIGNAL K-		
	18 SIGNAL E-	18 SIGNAL E-'	46	SIGNAL J+					46 SIGNAL J+		
	19 SIGNAL F-	19 SIGNAL F-'	47	SIGNAL H-					47 SIGNAL H-		
\vdash	20 SIGNAL G+	20 SIGNAL G+'	48	SIGNAL G+					4B SIGNAL G+		
	21 SIGNAL H+	21 SIGNAL H+'	49	SIGNAL E+					49 SIGNAL E+		
	22 SIGNAL I+	2E SIGNAL 1+'	50						50 SIGNAL D-		
A	23 SIGNAL J+	23 SIGNAL J+'	51	SIGNAL B+					51 SIGNAL B+		
	24 SIGNAL K+	24 SIGNAL K+'		•						42	10000700
	25 SIGNAL L+	25 SIGNAL L+'							<u> </u>	A 1 2383	10209722 _B
	12 11	10 0	8				5		3	ME HIME	NCLASSIFIED PETE FJ
	14	10 9	•				3	4			1

Attachment of HRCR Item #11:

SPIRE

Handling Document

Field Effect Transistor (JFET) Module

10209750-1

Prepared by: Kalyani Sukhatme

10 September, 2003

Hardware Handling Guidelines

Contamination: Open shipment suitcase in a FED-STD-209 Class 10,000 clean room (ISO 14644-1 class 7) or better. Handle hardware with gloves.

ESD: Handle with grounding straps, ESD-safe gloves and ESD smocks at an ESD-safe workstation. Maintain shorting plugs on the unit whenever ESD is a concern. Refer to attached electrical handling document for other important safety precautions.

Fragile: Do not drop or otherwise shock the hardware including the shipping suitcase and container.

Humidity Sensitive: Place hardware in a humidity controlled Class 10,000 clean room. Maintain humidity level at 35%-50% RH typical, for ESD safety.

SPIRE JFET Electrical Handling Document

1	Int	troduction	.1
	1.1	Hardware Description	.1
2	Ha	andling	.2
3	Po	ower ON Procedure	.2
4	Ele	ectrical Check-out Test: Characteristic Offset Voltage Measurement	.3

1. Introduction

This document provides guidelines for electrical handling for the SPIRE JFET Module.

1.1 Hardware Description

Each JFET module has two sets of 24 JFET channels. The JFET channels are populated on 1.0 micron thick Silicon Nitride membranes which provides thermal isolation. The operating temperature for these JFETs is ~120 K. The process of powering up the JFETs dissipates heat into the membrane resulting in a temperature increase with respect to the base temperature (4K to 10 K). Higher the power dissipation, higher is the temperature of the JFETs.

Each JFET channel consists of a matched pair of FETs (Figure 1.1-1) with a requirement for the offset voltage of less than **15 mV** between the matched pair. [The characteristic offset voltage is the difference between the source voltages $(V_{sa} \text{ and } V_{sb} \text{ with respect to ground})$ of the two FETs.]

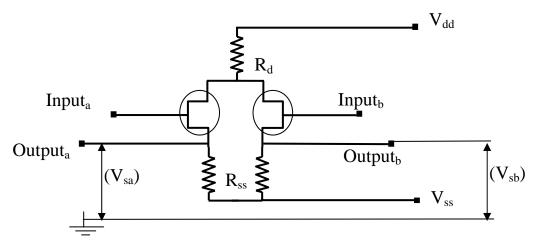


Figure 1.1-1

The Gates of the JFETs are the 'Inputs' of the circuit and the Sources (V_{sa} and V_{sb}) of the JFETs are the outputs, as marked in Figure 1.1-1. Vdd and Vss are the power lines for the circuit.

Handling

- 1. **The JFET Module is Contamination Sensitive**: Handle the unit with Gloves only in a FED-STD-209 Class 100000 clean room (ISO 14644-1 class 7) or better.
- 2. **The JFET Module is ESD Sensitive**: Please handle with appropriate ESD hardware handling procedures. Handle with grounding straps, ESD-safe gloves, ESD smocks at an ESD-safe workstation.
- 3. **The JFET Module is Fragile**: Please do not drop or otherwise shock the unit. Please DO NOT remove the cover of the JFET Module.

Power ON Procedure

1. The JFET Module should be powered on **WITH the shorting plugs** (JPL Supplied Protection connectors) in place and with the **inputs shorted to ground.** Pins #9 and #15 on the 15-pin MDM connectors on the JFET Module are the bias grounds on the module. These pins should also be shorted to the power supply ground. The unit may be powered up without the shorting plug only when the inputs are connected to the detector system.

Under no circumstances the unit should be powered up without the inputs shorted to ground either via the shorting plug (JPL Supplied) or via the detector system.

- 2. Do not exceed a voltage of +5 V for the Vdd line and -5 V for the Vss line of the JFET Module.
- 3. When removing the shorting plugs from the unit for installation into the instrument, please use standard ESD precautions including grounding straps, ESD-safe gloves, ESD smocks at an ESD-safe workstation.

Electrical Check-out Test: Characteristic Offset Voltage Measurement

- 1) Verify that the gates of the JFET channels (Inputs) are shorted together and grounded.
- 2) Apply the power supply ground to the bias ground pins on the unit (Pins 9 and 15 on the 15-pin MDM connectors)
- 3) Power on the JFET modules with Vdd = +3 V and Vss = -1.5 V
- 4) Verify that the handheld multimeter is in calibration.
- 5) Connect one side of the handheld multimeter to ground (Power supply ground).
- 6) And measure the voltage with respect to ground of each side (V_{sa} and V_{sb}) of each channel.
- 7) Calculate the characteristic offset voltage (V_{offset}) for each channel ($V_{offset} = V_{sa} V_{sb}$)
- 8) Compare the values for each of the channels with the specific datasheet provided with the unit. The datasheets accompanying the unit also provides the values for the drain and source currents for a similar test performed at JPL.

REFER TO MEASURED SOURCE VOLTAGE DATA FOR ACTUAL HARDWARE. Here is an example of the source voltage values and the drain and the source currents obtained for such a test at room temperature are given in the Table 4-1

T, JFET	rm T				
Vdd	3 V				
Vss	-1.5 V				
ldd	1.564 mA				
lss	1.5686 mA				
Channel #	(V)	DELTA (V)			
1	1.130	0			
1	1.130	U			
2	1.075	0.001			
2	1.074	0.001			
2	0.781	0.001			
3	0.780	0.001			
4	1.088	0.005			
4	1.093	0.005			
5	0.834	0.001			
3	0.833	0.001			
6	1.012	0.003			
0	1.015	0.003			
7	0.785	0.002			
/	0.787	0.002			
8	1.148	0.004			
0	1.144	0.004			
9	0.753	0			
9	0.753	U			

_	_			
10	0.693	0.008		
	0.701	0.000		
11	1.110	0.004		
11	1.114	0.004		
12	0.758	0.001		
12	0.759	0.001		
13	0.832	0.002		
- 10	0.830	0.002		
14	1.264	0.001		
1.	1.265	0.001		
15	1.206	0		
	1.206			
16	0.818	0.001		
	0.819	0.001		
17	0.526	0.005		
	0.521	0.000		
18	1.423	0		
	1.423			
19	0.773	0.002		
	0.775	0.002		
20	0.873	0.004		
-	0.877			
21	1.387	0.006		
	1.393			
22	1.417	0.003		
	1.420			
23	0.887	0.002		
	0.889			
24	0.888	0.003		
	0.891			

- END OF Attachment of HRCR Item # 11: JFET Module Handling Document

END OF HRCR PACKAGE